

MRF24WG0MA/MB

Pin Diagram

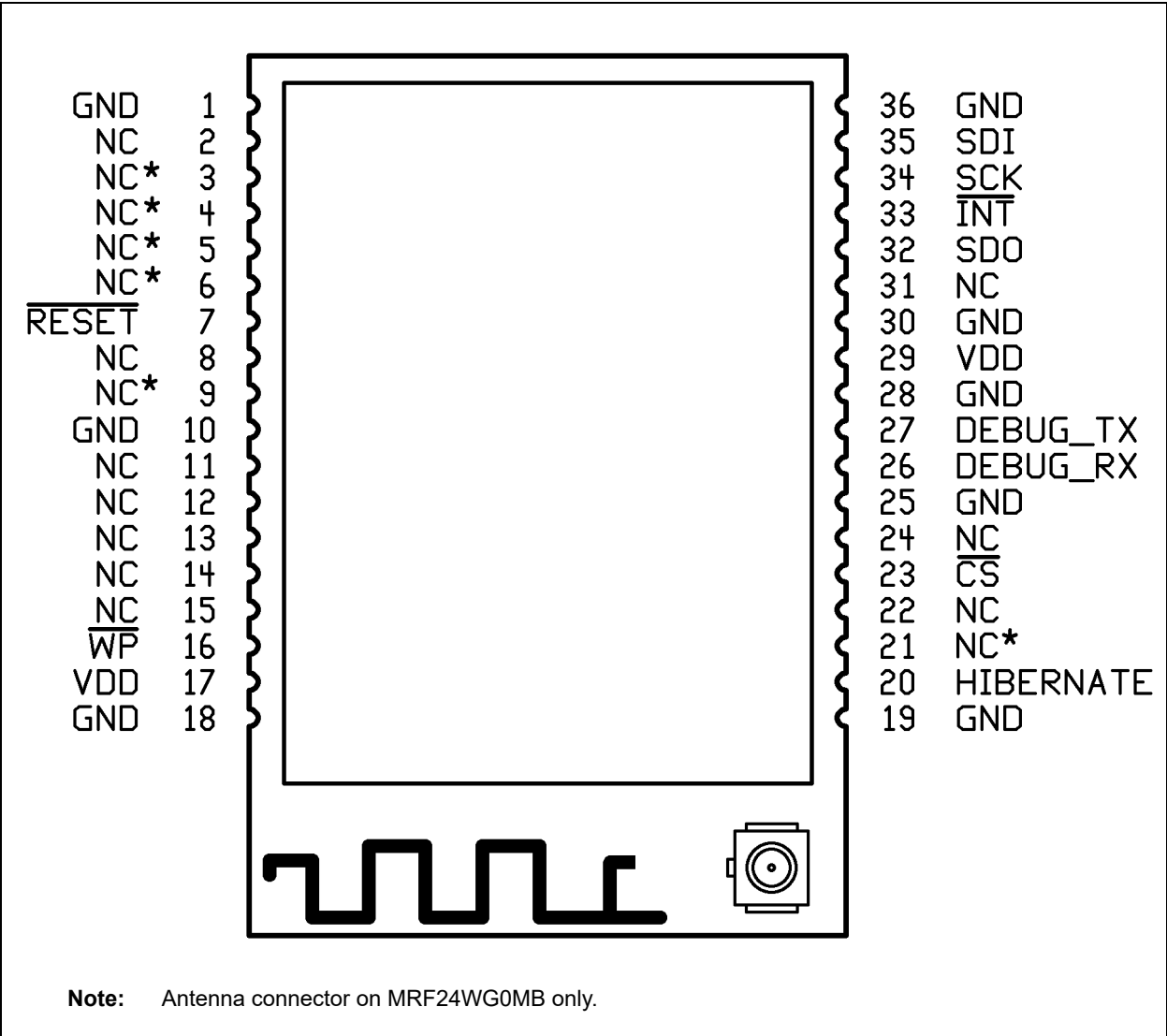


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MRF24WG0MA/MB

NOTES:

1.0 DEVICE OVERVIEW

The MRF24WG0MA and MRF24WG0MB are low-power, 2.4 GHz, IEEE 802.11-compliant, surface mount modules with all associated RF components – crystal oscillator, bypass and bias passives with integrated MAC, baseband, RF and power amplifier and built-in hardware support for AES and TKIP (WEP, WPA, WPA2 security). The modules also provide acceleration for hosts running WPA-EAP application security. The integrated module design frees the designer from RF and antenna design tasks and regulatory compliance testing, ultimately providing quicker time to market.

The MRF24WG0MA module is approved for use with the integrated PCB meander antenna.

The MRF24WG0MB module comes with an ultra-miniature coaxial connector (U.FL) and is approved for use with a list of antenna types that are certified with the module. See **Section 2.7 “External Antenna”** for specific recommendations.

The MRF24WG0MA/MB modules are designed to be used with Microchip’s TCP/IP software stack. The software stack has an integrated driver that implements the API that is used in the modules for command and control, and for management and data packet traffic.

The Microchip TCP/IP software stack is available in the free *Microchip Application Libraries* download (including example applications and source code) from the Microchip web site, <http://www.microchip.com/wireless>.

The combination of the module and a PIC running the TCP/IP stack results in support for IEEE Standard 802.11 and IP services. For example, this allows the immediate implementation of a wireless web server and e-mail clients.

The MRF24WG0MA/MB modules have received regulatory approvals for modular devices in the United States (FCC), Canada (ISED) and Europe (RED). The modular approval removes the need for expensive RF and antenna design, and allows the end user to place the modules inside a finished product and not require regulatory testing for an intentional radiator (RF transmitter). See **Section 3.0 “Regulatory Approval”** for the specific requirements that should be adhered to by the integrator.

1.1 Interface Description

The block diagram in [Figure 1-1](#) represents a MRF24WG0MA/MB module. It interfaces to Microchip PIC18, PIC24, dsPIC33 or PIC32 microcontrollers through a four-wire serial client SPI interface – interrupt, hibernate, reset, power and ground signals. The module runs on a single supply voltage of nominally 3.3V. The serial trace port operates at 3.3V and requires a level shifter for operation with RS-232 devices. This port provides a serial output of module status messages and is helpful for debugging purposes. [Figure 1-2](#) shows a simplified example connection between a Microchip PIC® MCU and the module. [Table 1-1](#) lists the pin descriptions.

Data communications with the MRF24WG0MA/MB are through the SPI interface that is detailed in **Section 2.0 “Circuit Description”**. The Microchip PIC microcontroller communicates with the module through a command API from within the Microchip TCP/IP stack. The command API is detailed in the Microchip TCP/IP stack online Help that is included in the free *Microchip Application Libraries* download.

MRF24WG0MA/MB

FIGURE 1-1: MRF24WG0MA/MB BLOCK DIAGRAM

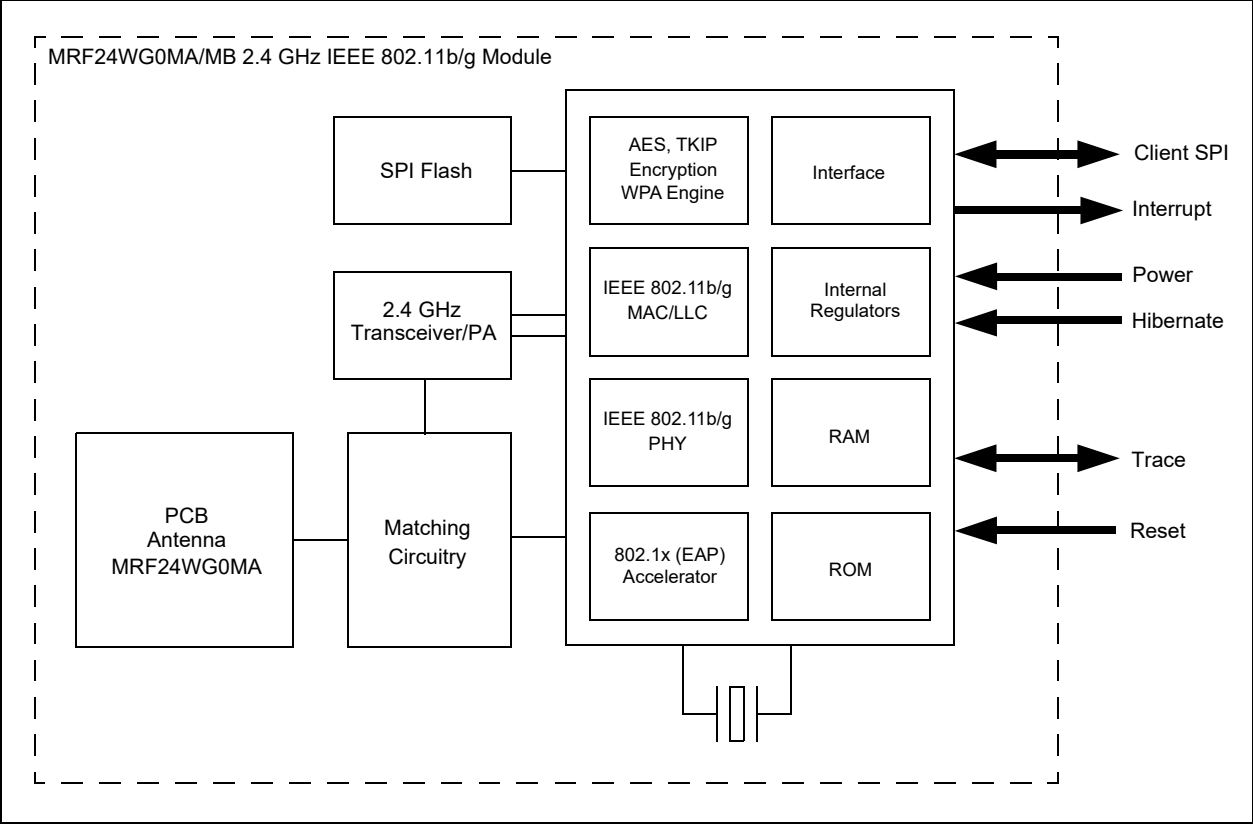


FIGURE 1-2: MICROCONTROLLER TO MRF24WG0MA/MB INTERFACE

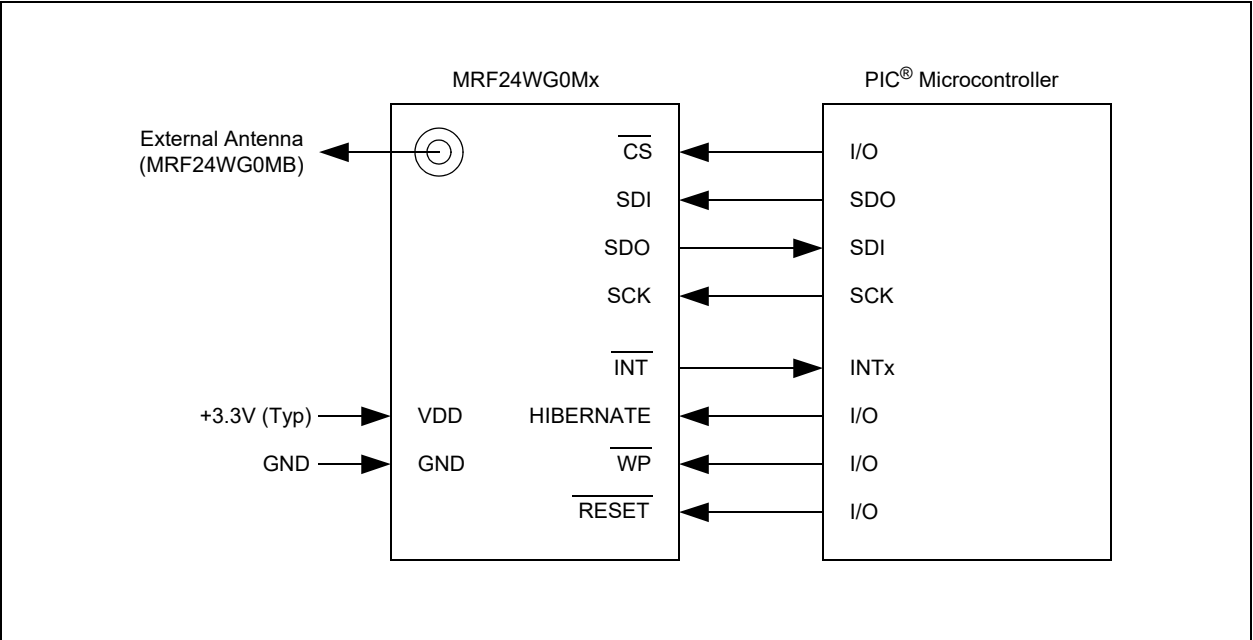


TABLE 1-1: Pin Description

Pin	Symbol	Type	Description
1	GND	P	Ground
2	NC*	NC*	No connect ⁽³⁾
3	NC*	NC*	No connect ⁽³⁾
4	NC*	NC*	No connect ⁽⁴⁾
5	NC*	NC*	No connect ⁽³⁾
6	NC*	NC*	No connect ⁽³⁾
7	$\overline{\text{RESET}}$	I: Constant ⁽¹⁾	Module Reset input
8	NC	NC	Do not connect
9	NC*	NC*	No connect ⁽³⁾
10	GND	P	Ground
11	NC	NC	Do not connect
12	NC	NC	Do not connect
13	NC	NC	Do not connect
14	NC	NC	Do not connect
15	NC	NC	Do not connect
16	$\overline{\text{WP}}^{(2)}$	I	Write protect (this pin is used to enable FLASH update)
17	VDD	P	Power
18	GND	P	Ground
19	GND	P	Ground
20	HIBERNATE	I	Hibernate mode enable (high input will disable the module)
21	NC*	NC*	No connect ⁽³⁾
22	NC	NC	Do not connect
23	$\overline{\text{CS}}$	I: Constant ⁽¹⁾	SPI Chip Select input, constant drive or pull-up required
24	NC	NC	Do not connect
25	GND	P	Ground
26	DEBUGRX	I	Serial debug port input (see Section 2.0 “Circuit Description”)
27	DEBUGHTX	O	Serial debug port output (see Section 2.0 “Circuit Description”)
28	GND	P	Ground
29	VDD	P	Power
30	GND	P	Ground
31	NC	NC	Do not connect
32	SDO	O	SPI data out
33	$\overline{\text{INT}}$	O	Interrupt output (open drain – requires a pull-up)
34	SCK	I	SPI clock input
35	SDI	I	SPI data in
36	GND	P	Ground

Legend: Pin type abbreviation: P = Power Input, I = Input, O = Output, NC = Do Not Connect, NC* = No Connect

Note 1: Signals of Type “I: Constant” must either be constantly driven by the host or have a pull-up or pull-down (in case the host is likely to tri-state the signal during power down modes). The constant drive is used to ensure defined operation of the part and to minimize leakage current during low power modes.

2: $\overline{\text{WP}}$ is used as write-protect for the internal module SPI Flash. For production use, this pin should be pulled low. This pin can be controlled by the host microcontroller to enable in field Flash updates.

3: Signals of Type “NC*” were JTAG function pins on previous family devices. Signals on these pins will have no functional affect and will not impact the operation of this device.

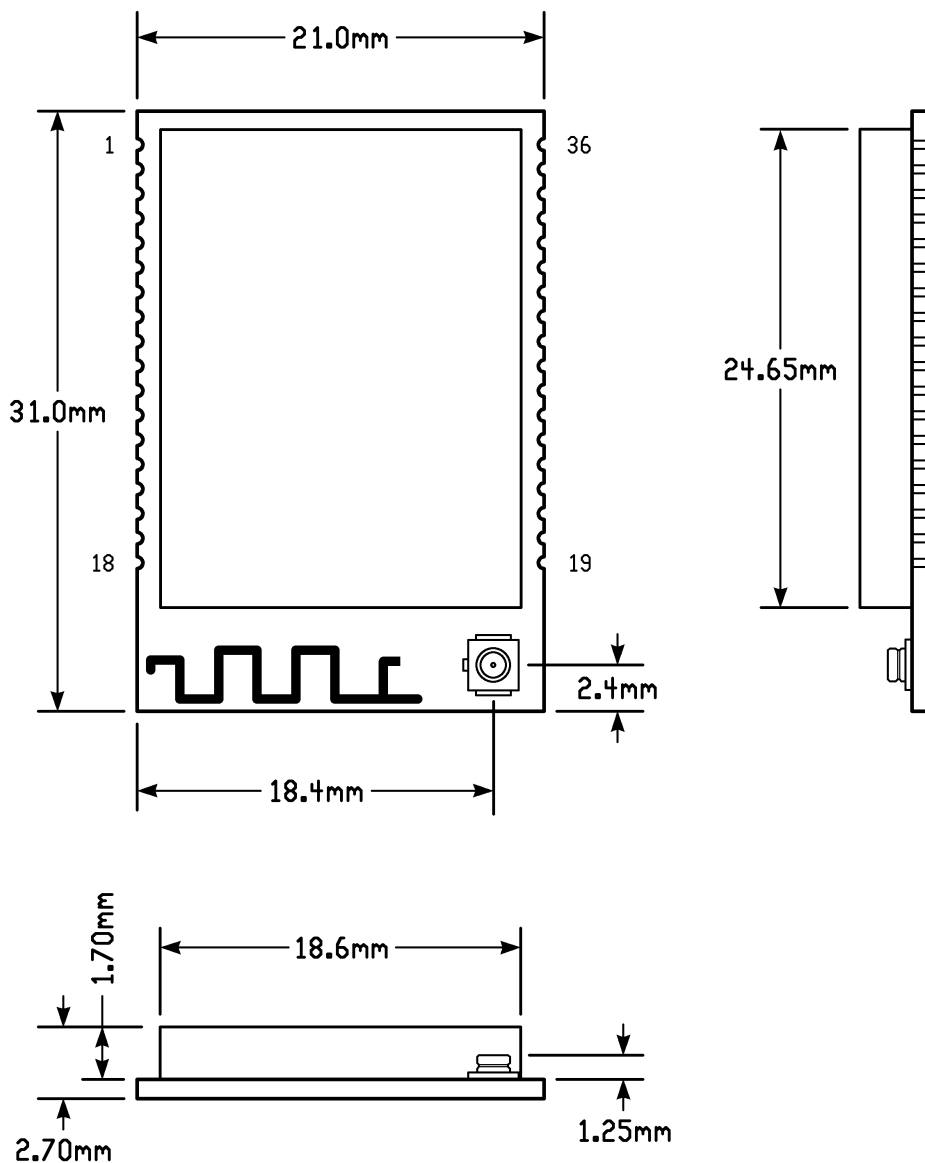
4: This signal should be left floating or pulled high only to support lowest 802.11PS power mode.

MRF24WG0MA/MB

1.2 Mounting Details

The MRF24WG0MA/MB is a surface mountable module. Module dimensions are shown in Figure 1-3. The module Printed Circuit Board (PCB) is 1 mm thick with castellated mounting points on two sides.

FIGURE 1-3: MRF24WG0MA/MB MODULE PHYSICAL DIMENSIONS



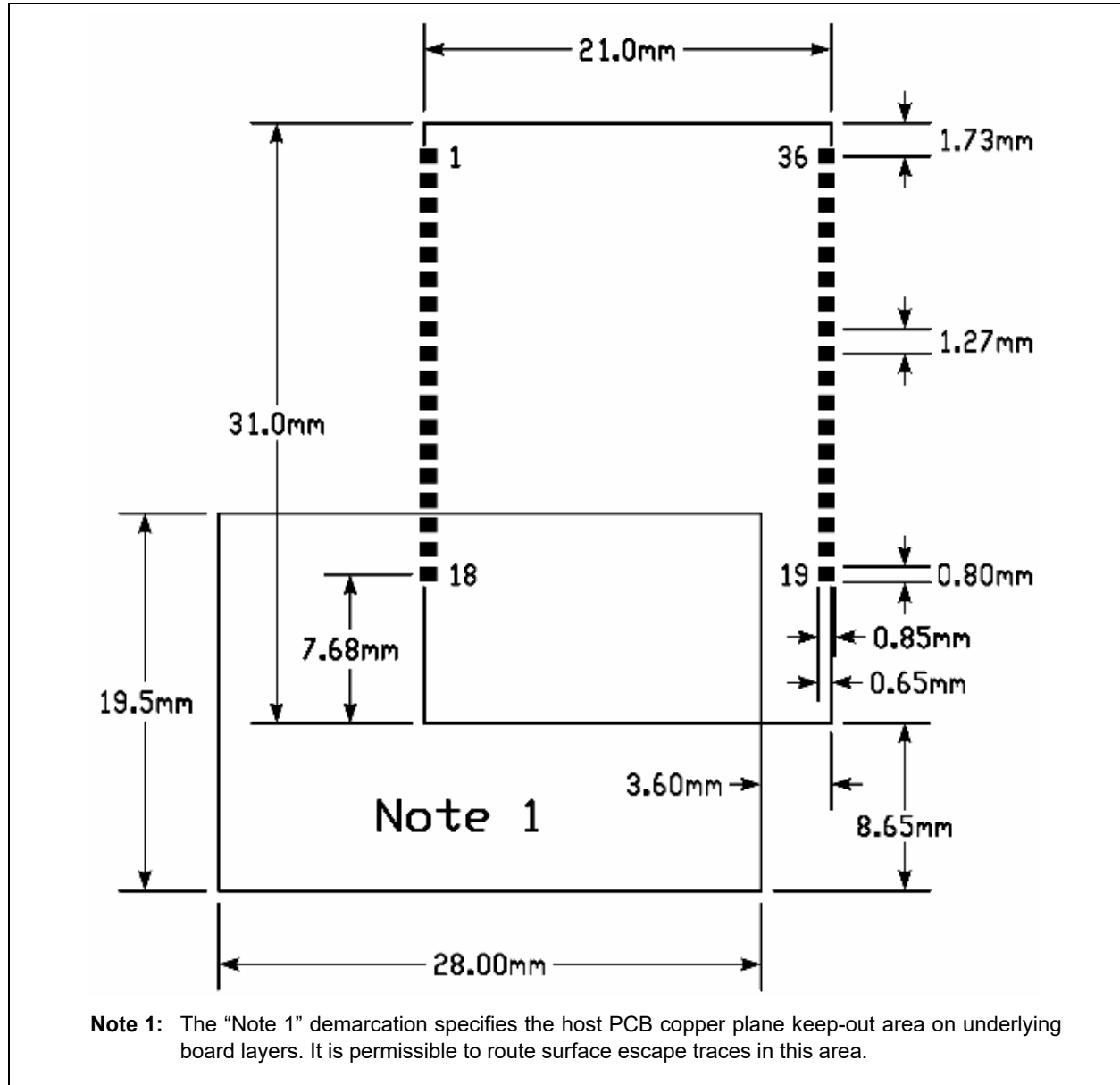
Note: Antenna connector on MRF24WG0MB only.

Figure 1-4 shows the recommended host PCB footprint for the module.

The MRF24WG0MA has an integrated PCB antenna. For best performance, follow the mounting details shown in Figure 1-4.

For best performance, mount the module on the PCB without metal obstructions in the keep out area of Figure 1-4. The antenna is tuned to have FR4 PCB material underneath the module. Do not “cut-out” host PCB material under the antenna.

FIGURE 1-4: RECOMMENDED HOST PCB FOOTPRINT



MRF24WG0MA/MB

Figure 1-5 illustrates the module reflow profile that is recommended for mounting the device onto the host PCB.

FIGURE 1-5: PRELIMINARY MODULE REFLOW PROFILE AND SETPOINTS

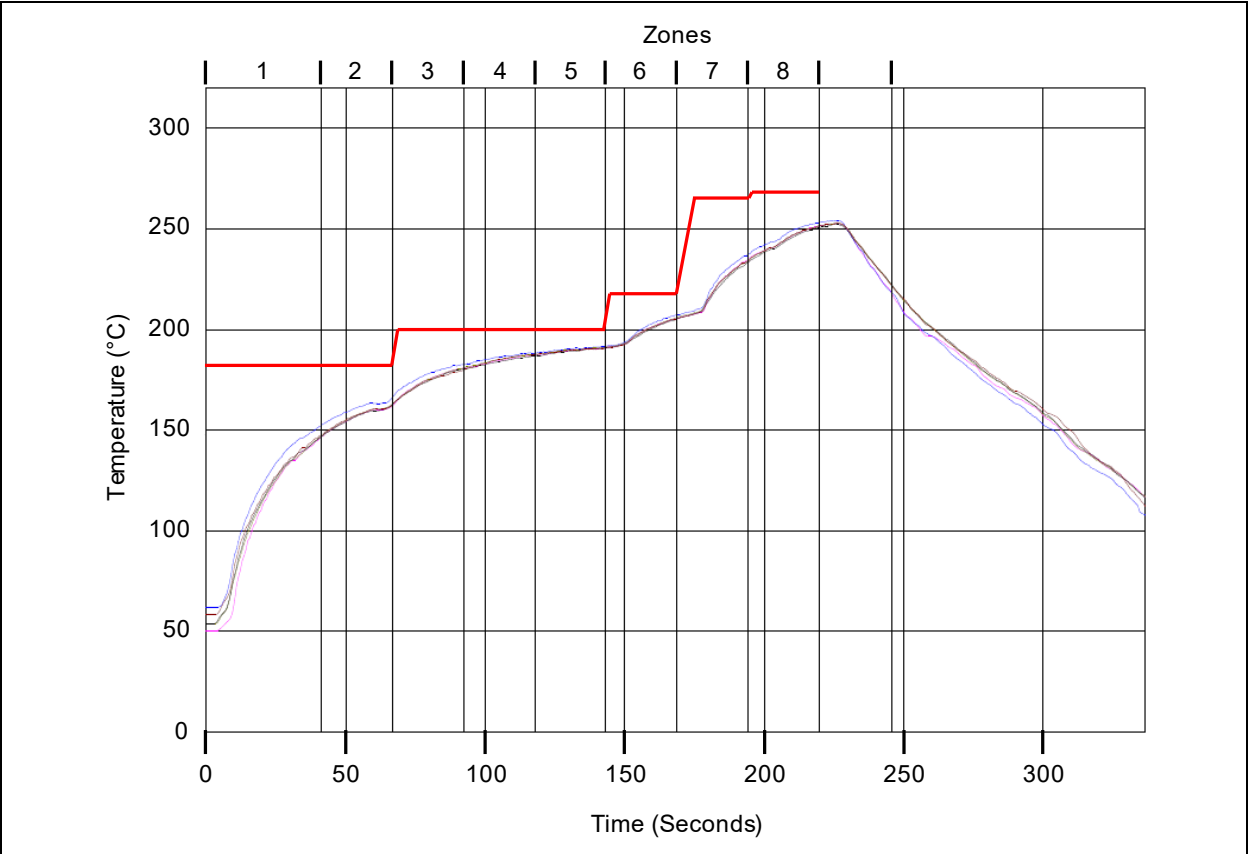


TABLE 1-2: MODULE REFLOW PROFILE⁽¹⁾

Zone	1	2	3	4	5	6	7	8
Temperature (°C)	180°	180°	200°	200°	200°	220°	265°	270°

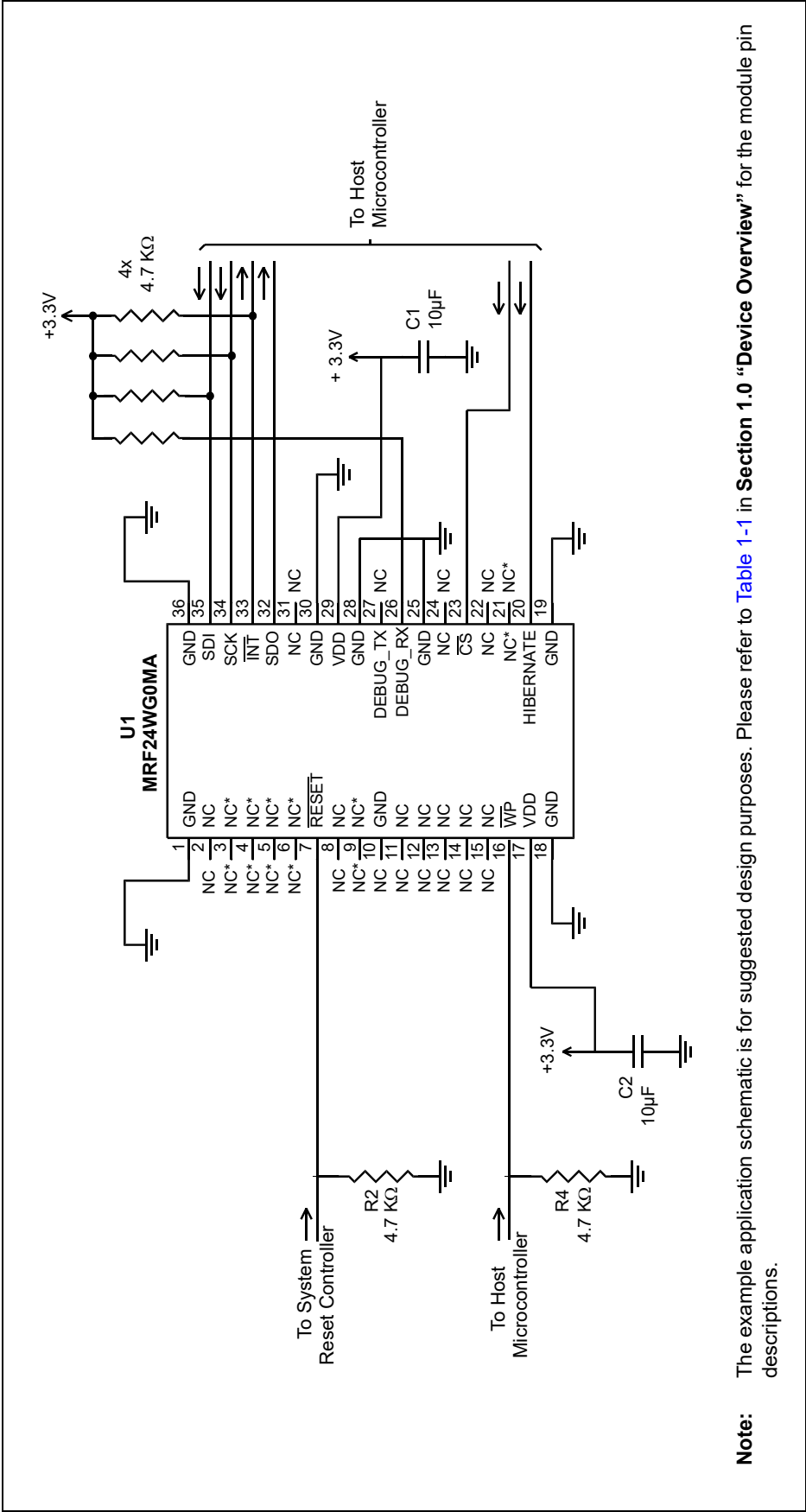
Note 1: Conveyor Speed: 90 cm/min

2.0 CIRCUIT DESCRIPTION

The MRF24WG0MA/MB interfaces to Microchip PIC18, PIC24, dsPIC33 and PIC32 microprocessors with a minimal of external components through digital-only connections. This section details use of the module, starting with an example host connection as shown in [Figure 2-1](#).

2.1 Schematic

FIGURE 2-1: MRF24WG0MA/MB EXAMPLE APPLICATION SCHEMATIC



MRF24WG0MA/MB

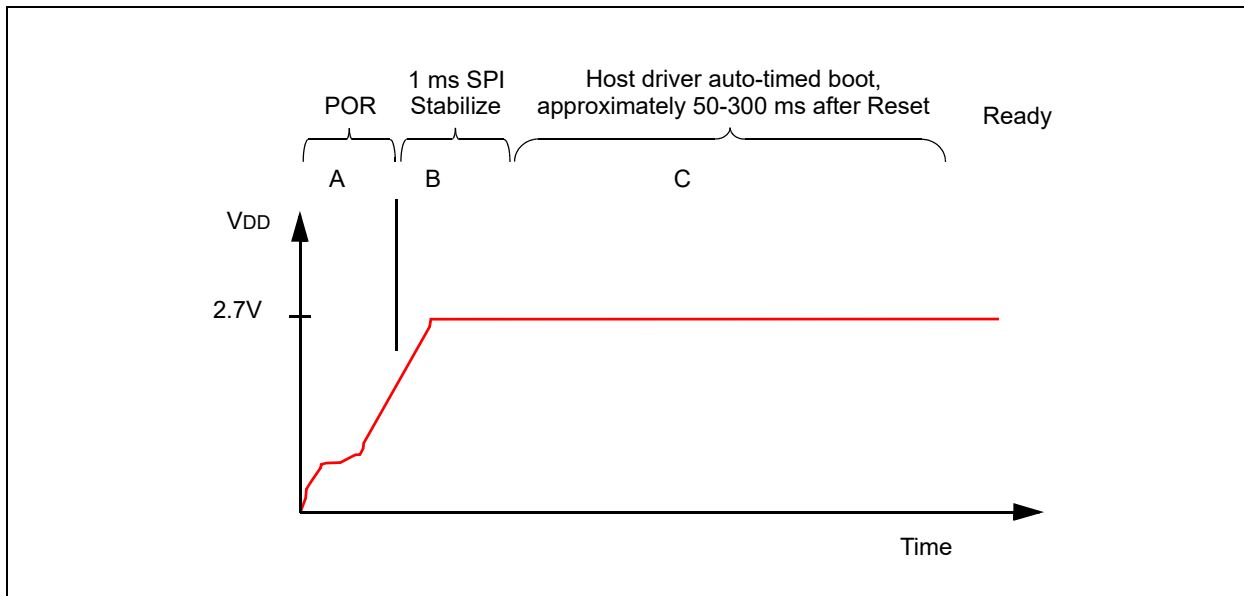
2.2 Power-On Sequence

The internal regulators for the digital and analog core power supplies are disabled by driving the HIBERNATE pin high. [Figure 2-2](#) shows the power up sequence for the MRF24WG0MA/MB.

There is an internal Power-on-Reset (POR) circuit which keeps the module in reset until VDD is within specification. The Hibernate and Reset signals are also used to control startup. In [Figure 2-2](#), section A is controlled by the internal POR and section B is an

allowance for the SPI bus to stabilize when the module supplies are enabled. Once Hibernate is disabled, the host software provides 1mS of startup to allow the SPI to stabilize. This time is pre-programmed into the host driver, and may need to be increased if sufficient initial drive current is not provided to the MRF24WG0MA/MB module. Section C is the driver controlled release from Reset period. This takes approximately 300 mS and is monitored by the stack driver. No additional time needs to be provided by user software for startup.

FIGURE 2-2: MRF24WG0MA/MB POWER-ON SEQUENCE TIMING



2.3 Power States

The MRF24WG0MA/MB has several power states. These are Hibernate, Sleep and Active (two sub-states), as shown in Figure 2-3. The selection of power state directly affects system behavior, and overall power consumption or battery life. There is also a “Stand-by” state that is not user-controlled.

2.3.1 HIBERNATE STATE

An “Off” state is defined as no power applied to the device. The Hibernate mode is the closest to controlled off that the module can approach. It is controlled through the HIBERNATE pin (high input puts the module into Hibernate). When in Hibernate, the module only consumes leakage current, but does not maintain state. Hibernate has to be fully controlled by the PIC MCU.

The module contains about 70 μF of internal bulk capacitance. Supplies should be provisioned to supply sufficient charge on release of hibernate for desired start time or sufficient delay must be provided in software after hibernate release and before releasing reset.

This state provides the best battery life for embedded products. Entering Hibernate for intervals of less than 1 minute is not likely to save power.

2.3.2 POWER SAVE (PS) MODE

The PS mode is a low-power dynamic state that automatically implements the 802.11 Power Save feature. In this mode, if enabled, the module will enter PS mode when all activity is complete.

The module will wake autonomously to any PIC intervention so it can check DTIM beacons from the Access Point. If any traffic is listed as queued for the module, then it will awake and get the data from the Access Point on the next possible opportunity. When data is acquired, the module will interrupt the PIC microcontroller on a normal “data available” indication. If no data is available on a DTIM check, the module reenters the Power Save state until the next DTIM. The DTIM interval is programmed at the Access Point. This state can provide “as if on” behavior of the radio with a significant power savings versus “always on”. The battery life expectation of this mode is several days to several weeks. This mode is characterized by a very low latency (as low as 200 ms) to begin data transfer from the state.

2.3.3 ACTIVE STATE

The Active state is identified as one of two states where the radio circuitry is fully on. The two active states are the Receive state (RX ON) and the Transmit state (TX ON).

2.3.4 STAND-BY STATE

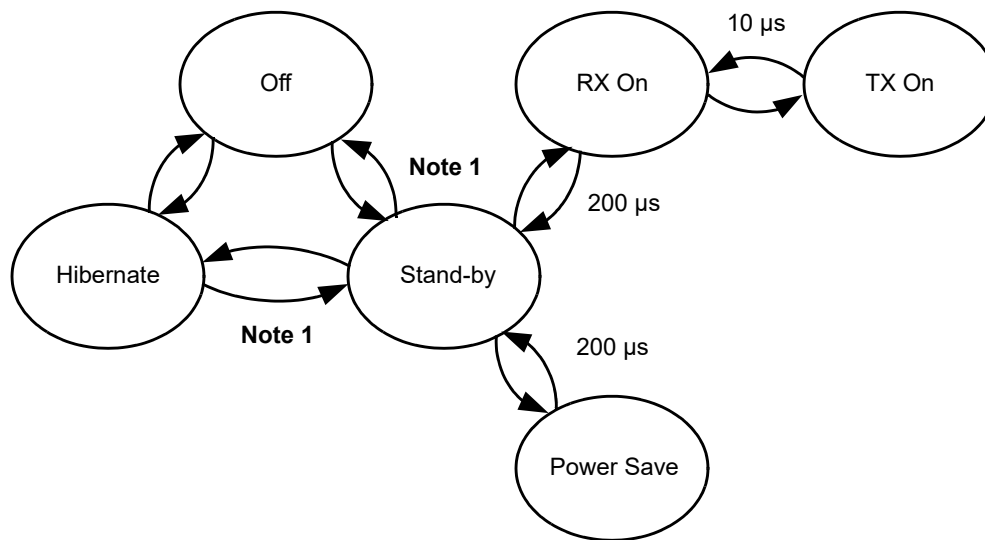
The Stand-by state is not user-controlled but is noted as it helps identify and track certain operations of the module during power tracing.

TABLE 2-1: MRF24WG0MA/MB POWER STATE DEFINITIONS

State	VDD	$\overline{\text{CS}}$	Description
Off	0V	0V	Power is completely disconnected
Hibernate	3.3V	3.3V	All internal power regulators are OFF – enabled by HIBERNATE pin
Power Save	3.3V	0V	Enabled by TCP/IP driver
RX ON	3.3V	0V	Receive circuits are on and receiving
TX ON	3.3V	0V	Transmit circuits are on and transmitting
Stand-by	3.3V	0V	State machine transition state only – not user controlled

MRF24WG0MA/MB

FIGURE 2-3: MRF24WG0MA/MB POWER-STATE DIAGRAM



Note 1: See Section 2.2 “Power-On Sequence”.

2.4 Serial Trace Port Interface

The MRF24WG0MA/MB incorporates a Transmit Data pin (DEBUGTx) and a Receive Data pin (DEBUGRx) for serial debugging purposes. These pins can be connected to commercially available RS-232 line drivers/receivers with appropriate external level shifters. The serial interface operates at 19200 (baud rate), 8 (data), N (parity), 1 (stop bit), N (flow control).

2.5 SPI Interface

The client Serial Peripheral Interface (SPI) is used to interface with the host PIC microcontroller. The client SPI interface works with the Interrupt line ($\overline{\text{INT}}$). When data is available for the PIC microcontroller during operation, the $\overline{\text{INT}}$ line is asserted (logic low) by the MRF24WG0MA/MB module. The $\overline{\text{INT}}$ line is deasserted (logic high) by the MRF24WG0MA/MB after the data is transferred to the host PIC microcontroller. The SPI SCK frequency can be up to 25 MHz.

The client SPI interface implements the [CPOL = 0; CPHA = 0] and [CPOL = 1; CPHA = 1] modes (0 and 3) of operation. That is, data is clocked in on the first rising edge of the clock after Chip Select ($\overline{\text{CS}}$) is asserted.

Data is placed on the bus with most significant bit (MSb) first.

The $\overline{\text{CS}}$ pin must be toggled with transfer blocks and cannot be held low permanently. The falling edge of $\overline{\text{CS}}$ is used to indicate the start of a transfer. The rising edge of $\overline{\text{CS}}$ is used to indicate the completion of a transfer.

Figure 4-1 in Section 4.0 “Electrical Characteristics” shows the SPI timing diagram. Table 4-7 details the SPI timing AC characteristics.

2.6 PCB Antenna

For the MRF24WG0MA, the PCB antenna is fabricated on the top copper layer and covered in solder mask. The layers below the antenna have no copper trace.

It is recommended that the module be mounted on the edge of the host PCB. It is permitted for PCB material to be below the antenna structure of the module as long as no copper traces or planes are on the host PCB in that area. For best performance, place the module on the host PCB according to the details shown in Figure 1-4 in Section 1.0 “Device Overview”.

The antenna patterns shown in the following plots are simulated results of the PCB antenna. Figure 2-4 illustrates the simulation drawing and Figure 2-5 and Figure 2-6 illustrate the two-dimensional (2D) and three-dimensional (3D) radiation patterns.

The calculated average of the radiated field is shown in Figure 2-5, highlighted in yellow. The radiation pattern for the XZ plane is shown in red, and the YZ plane is shown in black. As shown, the most powerful radiation occurs in the XY plane (the red pattern).

Figure 2-6 shows the relative position of the 3D radiation “donut” with reference to the module orientation. This is a very useful guide for placement of the module to obtain the maximum range.

Figure 2-7 shows the 3D radiation pattern with the colored distribution of the radiation magnitude. The values range from -9 dB to +0.3 dB. This is very useful in interpreting the 2D radiation pattern.

MRF24WG0MA/MB

FIGURE 2-4: PCB ANTENNA SIMULATION DRAWING

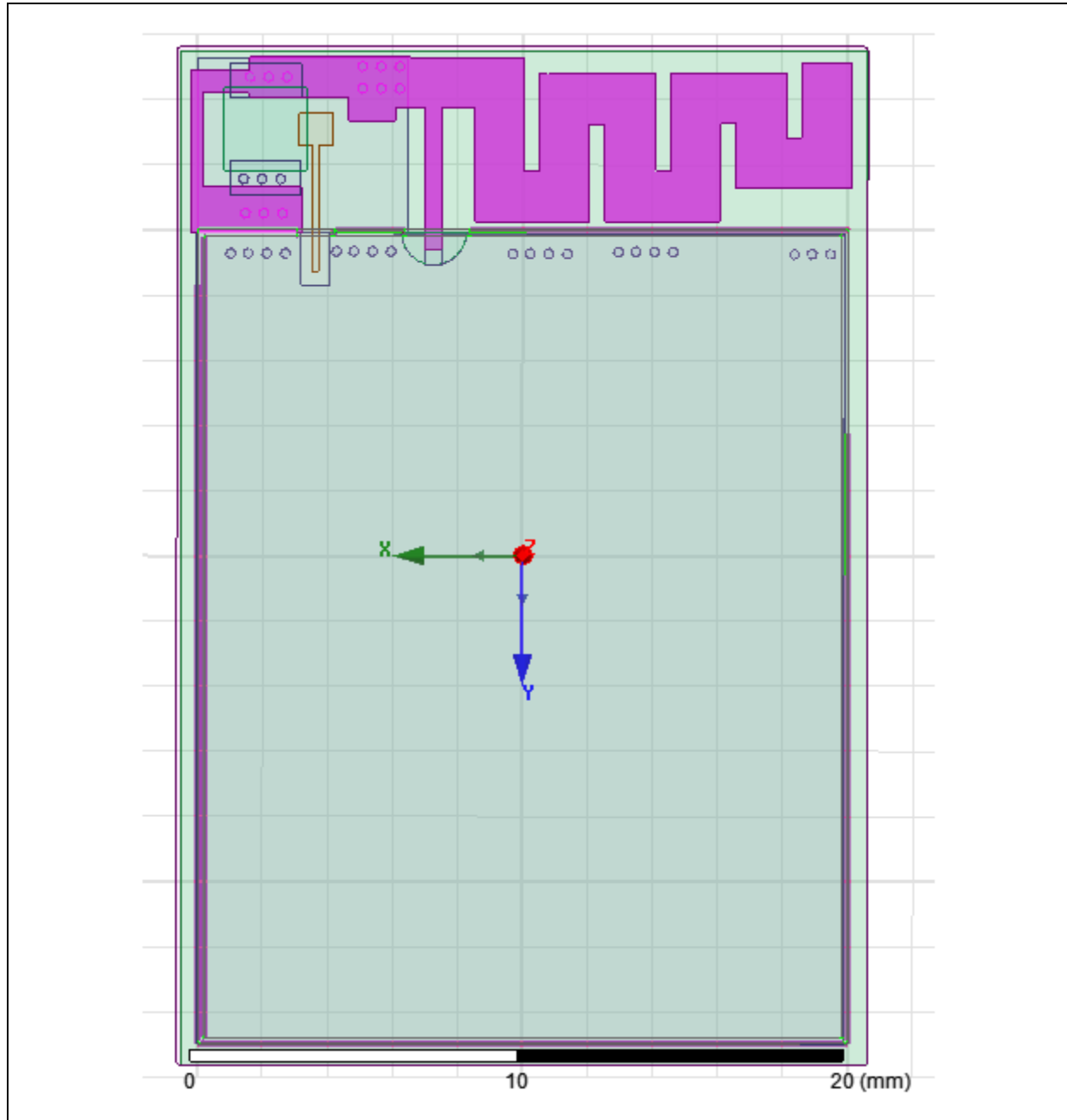
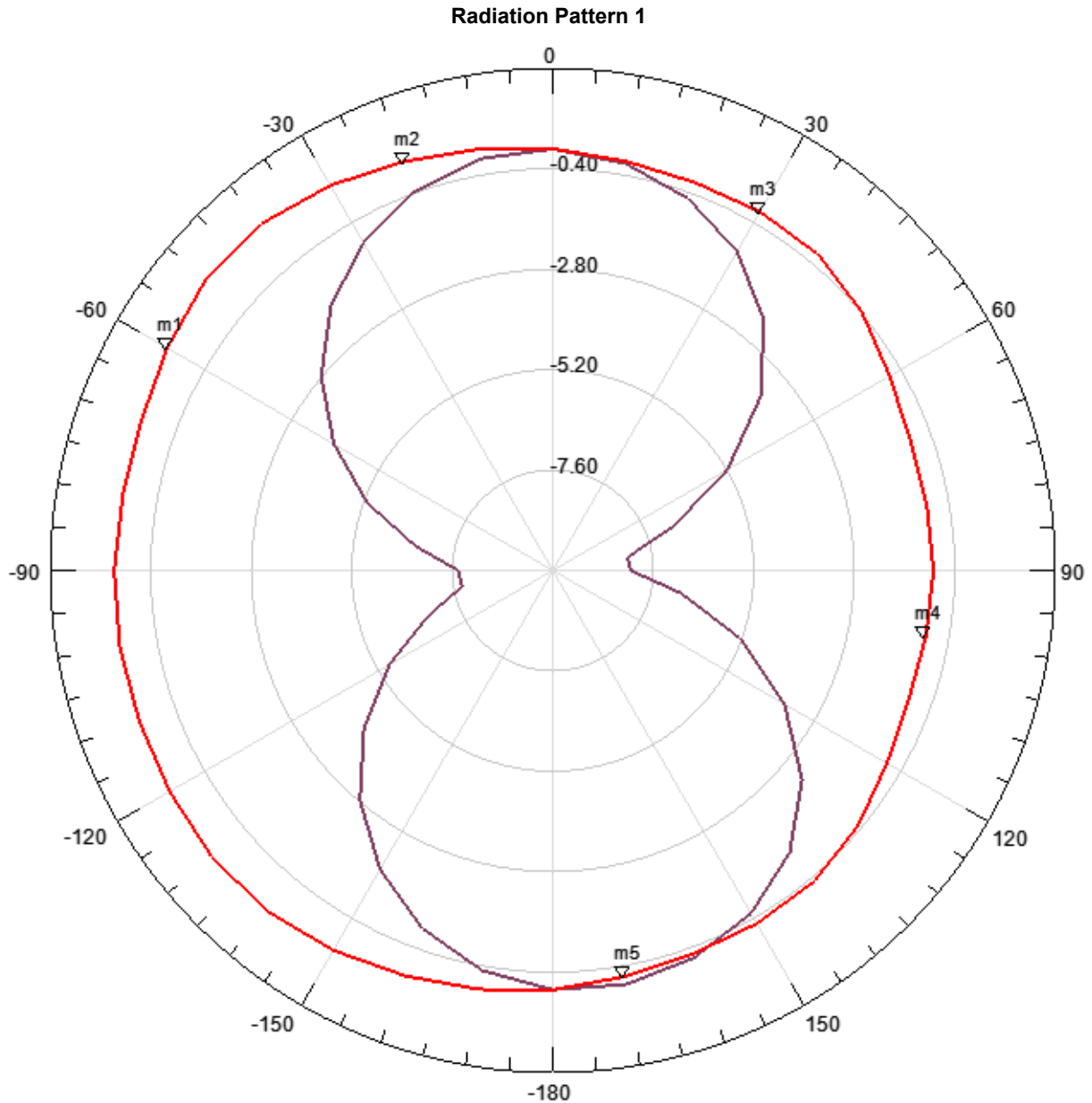


FIGURE 2-5: SIMULATED TWO-DIMENSIONAL RADIATION PATTERN

Name	Theta	Angle	Mag.
m1	-60.0000	-60.0000	0.6323
m2	-20.0000	-20.0000	0.3962
m3	30.0000	30.0000	-0.1038
m4	100.0000	100.0000	-0.9490
m5	170.0000	170.0000	-0.1414

Curve Information	Average
— db(GainTotal) Setup 1: LastAdaptive Freq. = "2.44 GHz" Phi = "0 deg"	0.0097
— dB(GainTotal) Setup 2: LastAdaptive Freq. = "2.44 GHz" Phi = "0 deg"	-3.2020



Two-dimensional (2D) pattern, including the average on main radiation planes (Phi = 0 and 90 degrees).

FIGURE 2-6: SIMULATED THREE-DIMENSIONAL RADIATION PATTERN

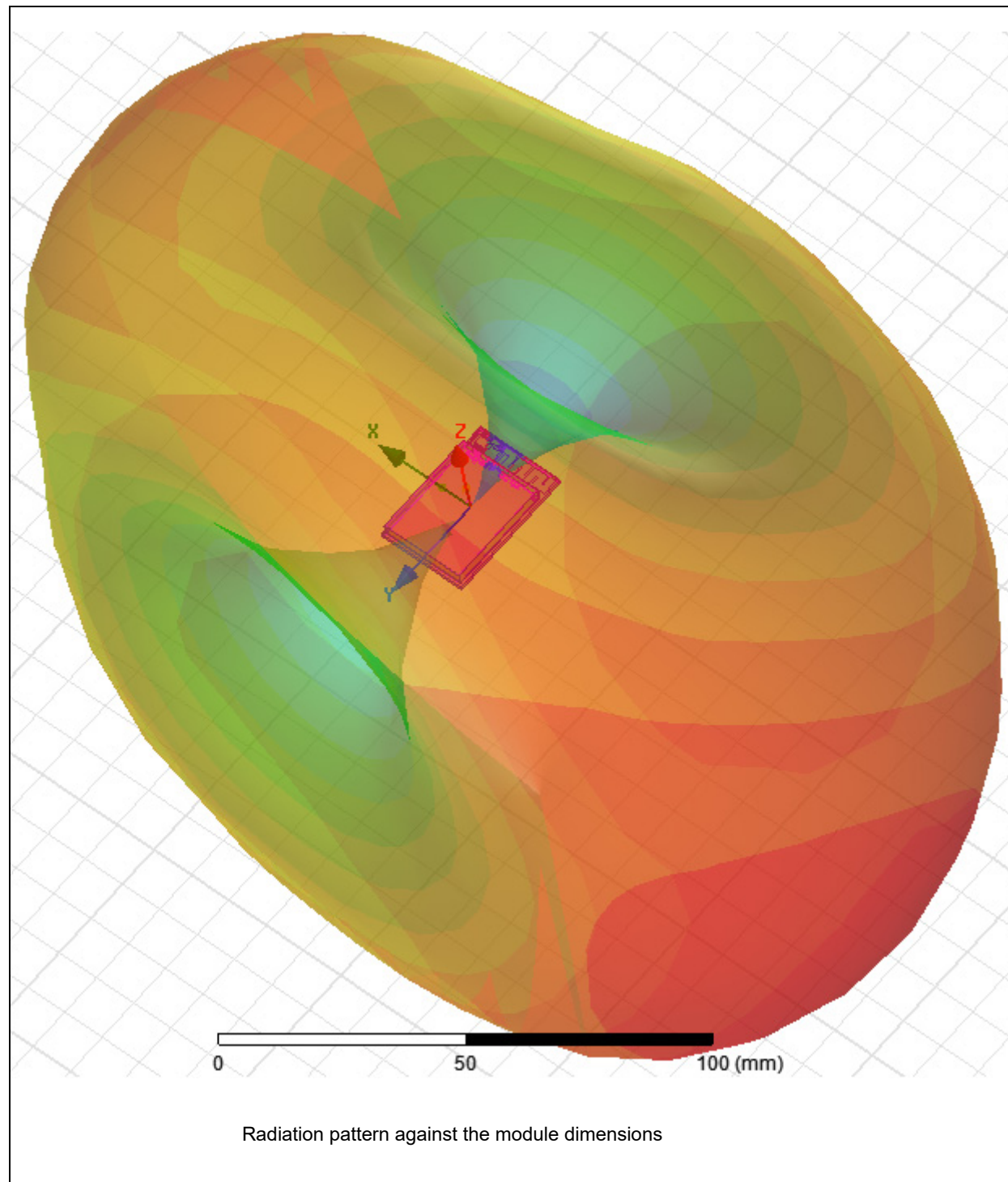
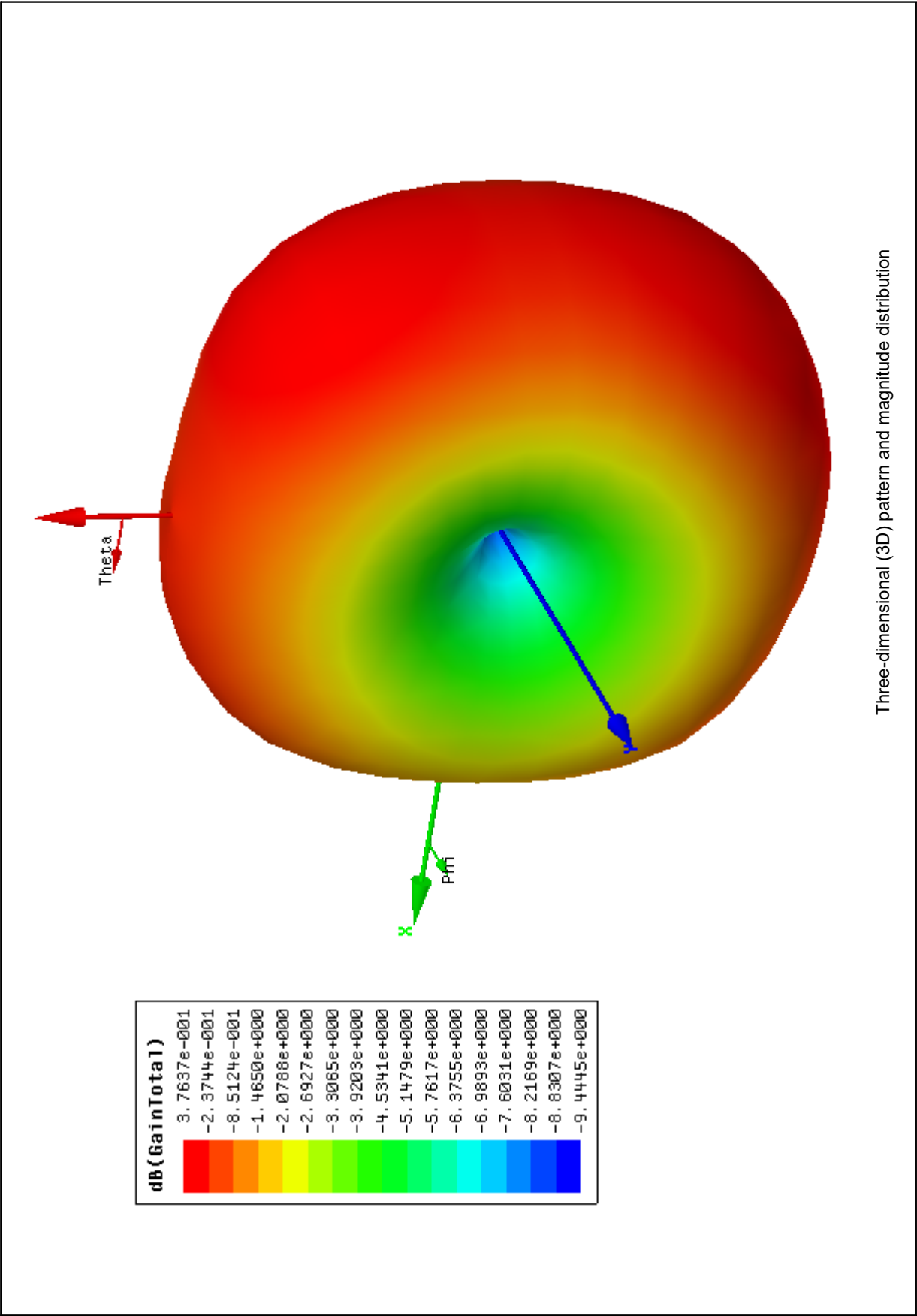


FIGURE 2-7: SIMULATED THREE-DIMENSIONAL RADIATION PATTERN



MRF24WG0MA/MB

2.7 External Antenna

The MRF24WG0MB module has a 50Ω ultra-miniature coaxial (U.FL) connector to connect to an external 2.4 GHz antenna.

Caution: The U.FL connector is fragile and can only tolerate a very limited number of insertions.

The choice of antenna is limited to the antenna types the module has been tested with. Refer to the respective country in **Section 3.0 “Regulatory Approval”** for a list of tested and approved antenna types that may be used with the MRF24WG0MB module.

A list of antennas approved for use with the module is provided in [Table 2-2](#).

TABLE 2-2: APPROVED EXTERNAL ANTENNA TYPES

Type	Manufacturer	Part Number	Gain
Dipole	Aristotle	RFA-02-C2M2-D034	2 dBi
PCB	Aristotle	RFA-02-P33-D034	1 dBi
PCB	Aristotle	RFA-02-P05-D034	2 dBi
PIFA	Aristotle	RFA-02-G03-D034	0 dBi

3.0 REGULATORY APPROVAL

The MRF24WG0MA/MB module has received regulatory approvals for modular devices in the United States and Canada. Modular approval allows the end user to place the MRF24WG0MA/MB module inside a finished product and not require regulatory testing for an intentional radiator (RF transmitter), provided no changes or modifications are made to the module circuitry. Changes or modifications could void the user's authority to operate the equipment. The end user must comply with all of the instructions provided by the Grantee, which indicate installation and/or operating conditions necessary for compliance.

The MRF24WG0MA/MB module has been tested and conforms to EN 300 328 V1.7.1 (2006-10), European Standards. The module tests can be applied toward final product certification and Declaration of Conformity (DoC). Additional testing may be required depending on the end application.

The integrator may still be responsible for testing the end product for any additional compliance requirements that become necessary with this module installed (for example, digital device emission, PC peripheral requirements, etc.) in the specific country that the end device will be marketed.

For more information on regulatory compliance, refer to the specific country radio regulations in the following sections.

3.1 United States

The MRF24WG0MA/MB has received Federal Communications Commission (FCC) CFR47 Telecommunications, Part 15 Subpart C "Intentional Radiators" 15.247 and modular approval in accordance with Part 15.212 Modular Transmitter approval. The MRF24WG0MA/MB module can be integrated into a finished product without obtaining subsequent and separate FCC approvals for intentional radiation.

The MRF24WG0MA/MB module has been labeled with its own FCC ID number, and if the FCC ID is not visible when the module is installed inside another device, then the outside of the finished product into which the module is installed must also display a label referring to the enclosed module. This exterior label can use wording as follows:

Contains Transmitter Module FCC ID:
W70MRF24WG0MAMB

or

Contains FCC ID:
W70MRF24WG0MAMB

This device complies with Part 15 of the FCC Rules. Operation is subject to the following two conditions:

(1) this device may not cause harmful interference, and (2) this device must accept any interference received, including interference that may cause undesired operation.

A user's manual for the product should include the following statement:

This equipment has been tested and found to comply with the limits for a Class B digital device, pursuant to part 15 of the FCC Rules. These limits are designed to provide reasonable protection against harmful interference in a residential installation. This equipment generates, uses and can radiate radio frequency energy, and if not installed and used in accordance with the instructions, may cause harmful interference to radio communications. However, there is no guarantee that interference will not occur in a particular installation. If this equipment does cause harmful interference to radio or television reception, which can be determined by turning the equipment off and on, the user is encouraged to try to correct the interference by one or more of the following measures:

- Reorient or relocate the receiving antenna.
- Increase the separation between the equipment and receiver.
- Connect the equipment into an outlet on a circuit different from that to which the receiver is connected.
- Consult the dealer or an experienced radio/TV technician for help.

MRF24WG0MA/MB

3.1.1 RF EXPOSURE

All transmitters regulated by FCC must comply with RF exposure requirements. OET Bulletin 65, *Evaluating Compliance with FCC Guidelines for Human Exposure to Radio Frequency Electromagnetic Fields*, provides assistance in determining whether proposed or existing transmitting facilities, operations or devices comply with limits for human exposure to Radio Frequency (RF) fields adopted by the Federal Communications Commission (FCC). The bulletin offers guidelines and suggestions for evaluating compliance.

If appropriate, compliance with exposure guidelines for mobile and unlicensed devices can be accomplished by the use of warning labels and by providing users with information concerning minimum separation distances from transmitting structures and proper installation of antennas.

The following statement must be included as a CAUTION statement in manuals and OEM products to alert users of FCC RF exposure compliance:

To satisfy FCC RF Exposure requirements for mobile and base station transmission devices, a separation distance of 20 cm or more should be maintained between the antenna of this device and persons during operation. To ensure compliance, operation at closer than this distance is not recommended.

The antenna(s) used for this transmitter must not be co-located or operating in conjunction with any other antenna or transmitter.

If the MRF24WG0MA/MB module is used in a portable application (i.e., the antenna is less than 20 cm from persons during operation), the integrator is responsible for performing Specific Absorption Rate (SAR) testing in accordance with FCC rules 2.1091.

3.1.2 APPROVED EXTERNAL ANTENNA TYPES

To maintain modular approval in the United States, only the antenna types that have been tested shall be used. It is permissible to use different antenna manufacturer provided the same antenna type and antenna gain (equal to or less than) is used.

Testing of the MRF24WG0MB module was performed with the antenna types listed in [Table 2-2](#) in **Section 2.0 “Circuit Description”**.

3.1.3 HELPFUL WEB SITES

Federal Communications Commission (FCC):
<http://www.fcc.gov>.

3.2 Canada

The MRF24WG0MA/MB module has been certified for use in Canada under Innovation, Science and Economic Development Canada (ISED, formerly Industry Canada) Radio Standards Specification (RSS) RSS-210 and RSSGen. Modular approval permits the installation of a module in a host device without the need to recertify the device.

3.2.1 LABELING AND USER INFORMATION REQUIREMENTS

Labeling Requirements for the Host Device (from RSP-100, Issue 12, Section 5): The host device shall be properly labeled to identify the module within the host device.

The Industry Canada certification label of a module shall be clearly visible at all times when installed in the host device, otherwise the host device must be labeled to display the Industry Canada certification number of the module, preceded by the words “Contains transmitter module”, or the word “Contains”, or similar wording expressing the same meaning, as follows:

Contains transmitter module IC: 7693A-24WG0MAMB

User Manual Notice for License-Exempt Radio Apparatus (from Section 8.4 RSS-Gen, Issue 5, March 2019): User manuals for license-exempt radio apparatus shall contain the following or equivalent notice in a conspicuous location in the user manual or alternatively on the device or both:

This device contains license-exempt transmitter(s)/ receiver(s) that comply with Innovation, Science and Economic Development Canada’s license-exempt RSS(s). Operation is subject to the following two conditions:

1. This device may not cause interference;
2. This device must accept any interference, including interference that may cause undesired operation of the device.

L’émetteur/récepteur exempt de licence contenu dans le présent appareil est conforme aux CNR d’Innovation, Sciences et Développement économique Canada applicables aux appareils radio exempts de licence. L’exploitation est autorisée aux deux conditions suivantes:

1. L’appareil ne doit pas produire de brouillage;
2. L’appareil doit accepter tout brouillage radioélectrique subi, même si le brouillage est susceptible d’en compromettre le fonctionnement.

Transmitter Antenna (From Section 6.8 RSS-GEN, Issue 5, March 2019): User manuals, for transmitters shall display the following notice in a conspicuous location:

This radio transmitter [IC:7693A-24WG0MAMB] has been approved by Innovation, Science and Economic Development Canada to operate with the antenna types listed below, with the maximum permissible gain indicated. Antenna types not included in this list that have a gain greater than the maximum gain indicated for any type listed are strictly prohibited for use with this device.

Le présent émetteur radio [IC:7693A-24WG0MAMB] a été approuvé par Innovation, Sciences et Développement économique Canada pour fonctionner avec les types d'antenne énumérés ci-dessous et ayant un gain admissible maximal. Les types d'antenne non inclus dans cette liste, et dont le gain est supérieur au gain maximal indiqué pour tout type figurant sur la liste, sont strictement interdits pour l'exploitation de l'émetteur.

Immediately following the above notice, the manufacturer shall provide a list of all antenna types approved for use with the transmitter, indicating the maximum permissible antenna gain (in dBi) and required impedance for each.

3.2.2 RF EXPOSURE

All transmitters regulated by ISED must comply with RF exposure requirements listed in RSS-102 - Radio Frequency (RF) Exposure Compliance of Radiocommunication Apparatus (All Frequency Bands).

3.2.3 APPROVED EXTERNAL ANTENNA TYPES

Transmitter Antenna (from Section 7.1.2 RSS-Gen, Issue 3, December 2010):

The MRF24WG0MA/MB module can only be sold or operated with antennas with which it was approved. Transmitter may be approved with multiple antenna types. An antenna type comprises antennas having similar in-band and out-of-band radiation patterns. Testing shall be performed using the highest gain antenna of each combination of transmitter and antenna type for which approval is being sought, with the transmitter output power set at the maximum level. Any antenna of the same type having equal or lesser gain as an antenna that had been successfully tested with the transmitter, will also be considered approved with the transmitter, and may be used and marketed with the transmitter.

When a measurement at the antenna connector is used to determine RF output power, the effective gain of the device's antenna shall be stated, based on measurement or on data from the antenna manufacturer. For transmitters of output power greater than 10 milli-

watts, the total antenna gain shall be added to the measured RF output power to demonstrate compliance to the specified radiated power limits.

Approved external antenna types for the MR24WB0MA/MRF24WB0MB module are listed in [Table 2-2](#).

3.2.4 HELPFUL WEB SITES

Industry Canada: <http://www.ic.gc.ca/>

MRF24WG0MA/MB

3.3 Europe

The MRF24WG0MA/MB module is Radio Equipment Directive (RED) assessed, CE marked, and have been manufactured and tested with the intention of being integrated into a final product.

The MRF24WG0MA/MB module has been tested to RED 2014/53/EU Essential Requirements mentioned in the following European Compliance table.

TABLE 3-1: EUROPEAN COMPLIANCE

Certification	Standards	Article
Safety	EN 62368	3.1a
Health	EN 62311	
Electro Magnetic Compatibility (EMC)	EN 301 489-1	3.1b
	EN 301 489-17	
Radio	EN300 328	3.2

The ETSI provides guidance on modular devices in “Guide to the application of harmonised standards covering Article 3.1b and Article 3.2 of the Directive 2014/53/EU RED to multi-radio and combined radio and non-radio equipment” document available at http://www.etsi.org/deliver/etsi_eg/203300_203399/203367/01.01.01_60/eg_203367v010101p.pdf.

Note: To maintain conformance to the standards listed in the preceding European Compliance table, the module shall be installed in accordance with the installation instructions in this data sheet and shall not be modified. When integrating a radio module into a completed product, the integrator becomes the manufacturer of the final product and is therefore responsible for demonstrating compliance of the final product with the essential requirements against the RED.

3.3.1 LABELING AND USER INFORMATION REQUIREMENTS

The label on the final product which contains the MRF24WG0MA/MB module must follow CE marking requirements.

3.3.2 CONFORMITY ASSESSMENT

From ETSI Guidance Note EG 203367, section 6.1 Non-radio products are combined with a radio product:

If the manufacturer of the combined equipment installs the radio product in a host non-radio product in equivalent assessment conditions (i.e. host equivalent to the one used for the assessment of the radio product) and according to the installation instructions for the radio product, then no additional assessment of the combined equipment against article 3.2 of the RED is required.

3.3.2.1 SIMPLIFIED EU DECLARATION OF CONFORMITY

Hereby, Microchip Technology Inc. declares that the radio equipment type MRF24WG0MA/MB is in compliance with Directive 2014/53/EU.

The full text of the EU declaration of conformity for this product is available at

<https://www.microchip.com/MRF24WG0MA>

(available under *Documents > Certifications*).

3.3.3 APPROVED ANTENNAS

For MRF24WG0MA/MB, the approval is received using the antenna shown in [Table 2-2](#).

3.3.4 HELPFUL WEB SITES

A document that can be used as a starting point in understanding the use of Short Range Devices (SRD) in Europe is the European Radio Communications Committee (ERC) Recommendation 70-03 E, which can be downloaded from the European Radio Communications Committee (ECC) at: <http://www.ecodocdb.dk/>.

Additional helpful web sites are:

- Radio Equipment Directive (2014/53/EU): https://ec.europa.eu/growth/single-market/european-standards/harmonised-standards/red_en
- European Conference of Postal and Telecommunications Administrations (CEPT): <http://www.cept.org>
- European Telecommunications Standards Institute (ETSI): <http://www.etsi.org>

The Radio Equipment Directive Compliance Association (REDCA): <http://www.redca.eu/>

3.4 Other Regulatory Jurisdictions

Should other regulatory jurisdiction certification be required by the customer, or the customer need to recertify the module for other reasons, a certification utility is available. The utility runs on a Window's PC and utilizes a USB to SPI converter to interface to the MRF24WG0MA/MB module. In order to use the utility, the MRF24WG0MA/MB module must be out of reset and not accessed by the system host. That is, the SPI signals to the MRF24WG0MA/MB module must be tri-state, with Reset and Hibernate deasserted. The following signals will need to be brought from the MRF24WG0MA/MB module for connection to the PC (through the USB adapter):

- SDO
- SDI
- $\overline{\text{CS}}$
- SCK
- $\overline{\text{INT}}$
- GND

For further regulatory Certification Utility and documentation, contact your local Microchip salesperson.

3.5 Wi-Fi® Alliance

Wi-Fi Alliance Certification focuses on interoperability testing of devices based on 802.11 standards.

Historically, when the certification process and programs were developed by Wi-Fi Alliance members, the vast majority of the 802.11 clients were PC-centric, and certification testing adequately addressed those types of devices. In subsequent years, the number of Wi-Fi devices that are not PC-centric has grown significantly.

These non-standard devices, as a class of products, have been dubbed Application Specific Devices (ASDs) by the Wi-Fi Alliance. ASDs are 802.11 devices, for example clients or access points (APs), which cannot be tested under a standard Alliance test plan because they do not comply with the standard test configuration and/or because they are designed to perform a specific application. Examples include, but are not limited to: bar code scanners, pagers, recording devices, monitoring equipment, and cable modems.

The APs or clients that are used to validate ASD compliance (from the standard test bed) will meet all of the requirements specified in the applicable System Interoperability Test Plans (referred to as the "standard test plan"), unless specifically exempted. The MRF24WG0MA/MB modules are in the ASD category.

The modules are certified under Wi-Fi 802.11 with ASD Model Test Plan with Test Engine For IEEE 802.11a, b, and g Devices (Version 1.0).

MRF24WG0MA/MB

NOTES:

4.0 ELECTRICAL CHARACTERISTICS

TABLE 4-1: DIGITAL ELECTRICAL CHARACTERISTICS (NOMINAL CONDITIONS: 25°C, V_{DD} = 3.3V)

Parameters	Min	Typ	Max	Units
V _{IL} (Input low voltage)	-0.3	—	0.8	V
V _{IH} (Input high voltage)	2	—	5.5	V
V _{OL} (Output low voltage)	—	—	0.4	V
V _{OH} (Output high voltage)	2.4	—	—	V
I _{OL} (Output low level current at V _{OL} Max)	—	8.5	—	mA
I _{OH} (Output high level current at V _{OH} Min)	—	15.4	—	mA

TABLE 4-2: ABSOLUTE MAXIMUM RATINGS⁽¹⁾

Parameters	Min	Max	Notes
Storage Temperature	-40°C	+125°C	—
V _{DD}	0V	3.60V	—
V _{IN} on SDI, $\overline{\text{CS}}$, SCK	-0.3V	3.60V	—

Note 1: The listed Absolute Maximum Ratings are not meant for functional operation. Operation exceeding these levels is not guaranteed, and may reduce the operating life of the component.

TABLE 4-3: RECOMMENDED OPERATING CONDITIONS

Parameters	Min	Typ	Max	Units
Ambient Temperature	-40	—	+85	Degrees Celsius
V _{DD} – for USA and Canada	2.80	3.3	3.60	Volts
V _{DD} – for Europe	3.0	3.3	3.60	Volts

TABLE 4-4: CURRENT CONSUMPTION⁽¹⁾ (NOMINAL CONDITIONS: 25°C, V_{DD} = 3.3V)

Parameters	Min	Typ	Max	Units	Conditions
I _{DD} , Hibernate = 3.3V	—	0.1	—	mA	—
I _{DD} , Power Save (software enabled)	—	4 ⁽²⁾	—	mA	—
I _{DD} , RX on, Receive @ -91 dBm with 1 Mbps modulated signal at antenna port	—	156	—	mA	—
I _{DD} , TX on, 802.11b, +18 dBm	—	237	—	mA	Measured at 11 Mbps
I _{DD} , TX on, 802.11g, +16 dBm	—	226	—	mA	Measured at 6 Mbps

Note 1: Current Consumption values represent Typical Peak currents, and the measured current conditions were done with 85% duty cycle modulated signal. Wi-Fi applications typically operate at less than 85% TX duty cycle. TX current is dependent on such criteria as transmit power setting, and transmit data rate and bandwidth being used. RX current is affected by connection distance.

2: Power Save current is current consumed during periods of “stand-by” between DTIM beacons. The module will awake 2 ms before a DTIM and turn on its receiver, and possibly its transmitter (if data is available).

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TABLE 4-5: RECEIVER AC CHARACTERISTICS⁽¹⁾

Parameters	Min	Typ	Max	Units
Flo	2412	—	2484	MHz
RX Min Input Level Sensitivity, 1 Mbps, 8% PER	—	-95	—	dBm
RX Min Input Level Sensitivity, 2 Mbps, 8% PER	—	-88	—	dBm
RX Max Input Level (Power), 1 Mbps, 8% PER	—	-4	—	dBm
RX Max Input Level (Power), 2 Mbps, 8% PER	—	-4	—	dBm

Note 1: Nominal conditions: 25°C, V_{DD} = 3.3V, Flo = 2437 MHz, measurements at antenna port.

TABLE 4-6: TRANSMITTER AC CHARACTERISTICS⁽¹⁾

Parameters	Min	Typ	Max	Units
Flo	2412	—	2484	MHz
Average P _{OUT} (transmit spectrum mask compliant)	—	+18	—	dBm
Average P _{OUT} gain step resolution from +5 to +10 dBm ⁽²⁾	—	0.5	—	dB
Average P _{OUT} gain step resolution from -5 to Max. ⁽²⁾	—	1.0	—	dB

Note 1: Nominal conditions: 25°C, V_{DD} = 3.3V, Flo = 2437 MHz, 2 Mbps. modulated signal measured at antenna port.

2: Gain step control is not calibrated. Steps are shown for planning purposes only.

FIGURE 4-1: SPI INPUT TIMING

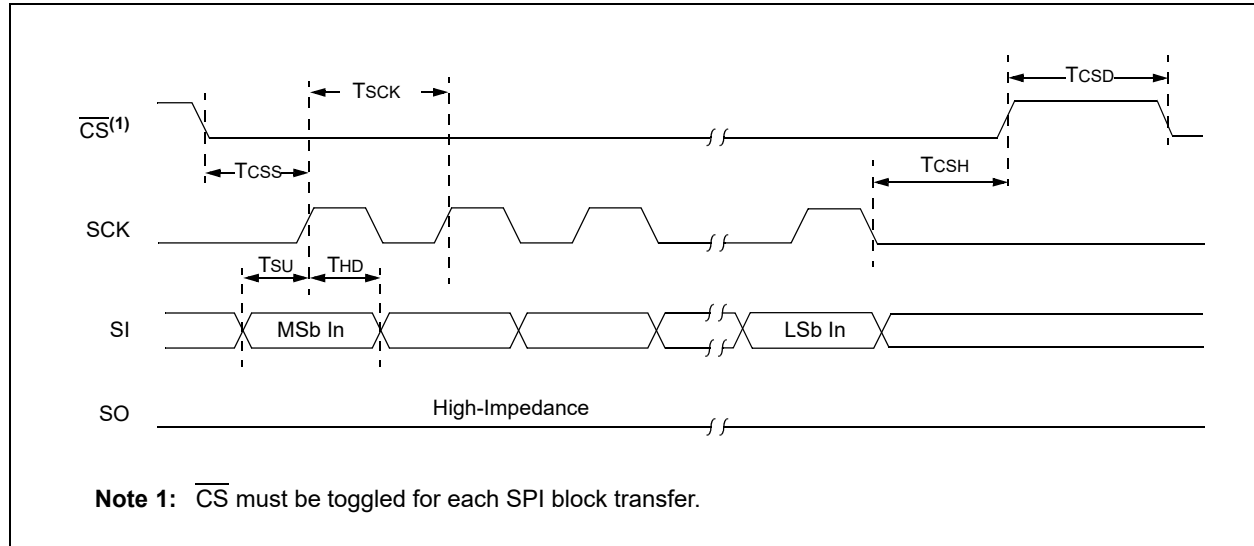


FIGURE 4-2: SPI OUTPUT TIMING

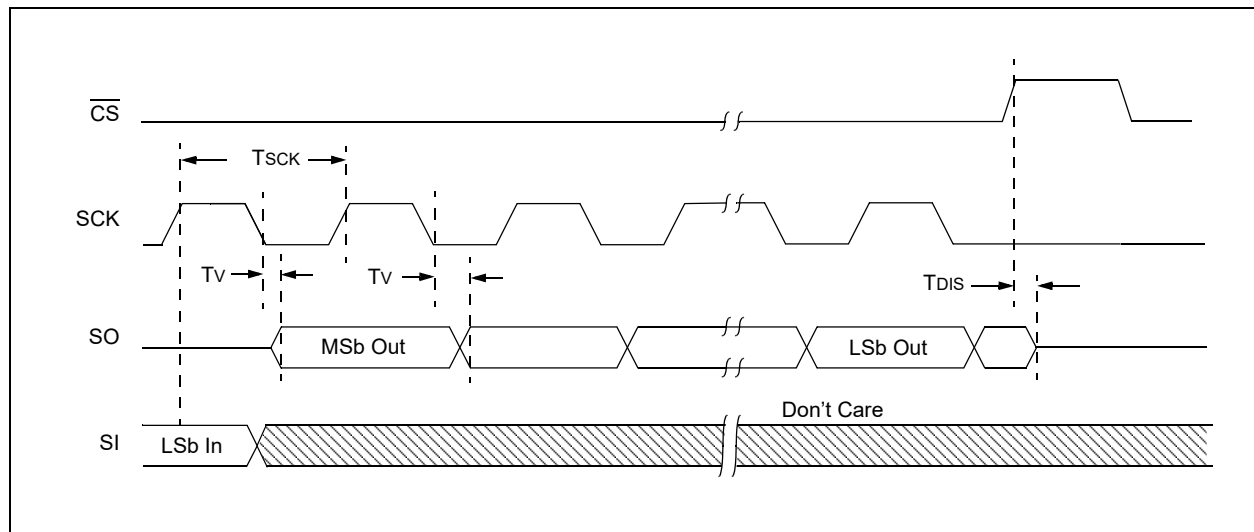


TABLE 4-7: SPI INTERFACE AC CHARACTERISTICS

Symbol	Parameters	Min	Max	Units
Tsck	SCK Period	40	—	ns
TcSD	$\overline{\text{CS}}$ High time	50	—	ns
Tcss	$\overline{\text{CS}}$ Setup time	50	—	ns
Tcsh	$\overline{\text{CS}}$ Hold time	50	—	ns
Tsu	SDI Setup time	10	—	ns
THD	SDI Hold time	10	—	ns
Tv	SDO Valid time	—	15	ns

MRF24WG0MA/MB

NOTES:

APPENDIX A: REVISION HISTORY

Revision A (August 2012)

This is the initial released version of the document.

Revision B (October 2012)

This revision includes the following updates:

- **TABLE 1-1: “Pin Description”** is updated and new note added
- **FIGURE 2-1: “MRF24WG0MA/MB Example Application Schematic”** is updated
- Updated the section **2.3.1 “Hibernate State”**

Revision C (May 2021)

- Updated **Section 3.3 “Europe”**
- Updated with the new terminologies. For more details, see the below note.

Note: Microchip is aware that some terminologies used in the technical documents and existing software codes of this product are outdated and unsuitable. This document may use these new terminologies, which may or may not reflect on the source codes, software GUIs and the documents referenced within this document. The following table shows the relevant terminology changes made in this document.

TABLE 1: TERMINOLOGY RELATED CHANGES

Old Terminology	New Terminology	Description
Slave	Client	• Section 1.1 “Interface Description” is updated with the new terminology. • Figure 1-1 is updated with the new terminology. • Section 2.5 “SPI Interface” is updated with the new terminology.

MRF24WG0MA/MB

NOTES:

PRODUCT IDENTIFICATION SYSTEM

To order parts, including industrial, or obtain information, for e.g., on pricing or delivery, refer to the factory or the listed sales office.

<u>PART NO.</u>	M	X	T	-X
Device	Module	Module Type	Tape and Reel	Temperature Range
Device	MRF24WG0MA/MB; VDD range 2.8V to 3.60V			
Temperature Range	I = -40°C to +85°C (Industrial Temperature)			

Examples:

a) MRF24WG0MA-I/RM = Industrial Temp

MRF24WG0MA/MB

NOTES:

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